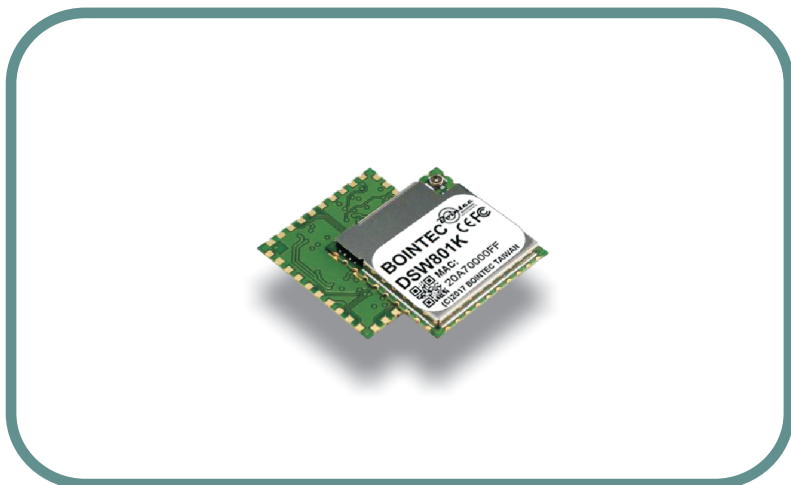




DSW801K

IEEE 802.11 b/g/n+BT4.2, SMT Type Module



DSW801K

802.11 b/g/n with Bluetooth 4.2 Combo 1T1R, SMT Type, IoT Wifi

Introduction of Products

DSW801K is a low-cost and low-power consumption IoT module. This stand-alone module is an operating system designed for wearable or internet of things (IoT) devices with smart connection and cloud application/services.

DSW801K is a highly integrated SIP module which features an application processor, a low power 1x1 11n singlw-band Wi-Fi subsystem, a Bluetooth subsystem, and a Power Management Unit. The application processor subsystem contains an ARM Cortex-M4F MCU, which has many peripherals, including UART, I2C, SPI, I2S, PWM, IrDA, and auxiliary ADC. DSW801K also includes embedded SRAM/ROM and an external 4MB serial flash.

The Wi-Fi subsystem contains the 802.11b/g/n radio, baseband, and MAC that are designed to meet both the low power and high throughput application. It also contains a 32-bit RISC CPU that could fully offload the application processor.

The Bluetooth subsystem contains the Bluetooth radio, baseband, link controller. It also uses the same 32-bit RISC CPU for the Bluetooth protocols.

Product Highlight

- Main Chip:MT7697
- Supports eXecute In Place (XIP) on flash
- 32KB cache in XIP mode
- Single-band 1T1R mode with data rate up to 150Mbps
- Supports STBC, LDPC
- Greenfield, mixed mode, legacy modes support
- Security :WFA WPA/WPA2 personal, WPS2.0, WAPI
- QoS support of WFA WMM, WMM PS
- Integrated LNA, PA, and T/R switch
- Optional external LNA and PA support.
- RX diversity support with additional RX input
- Bluetooth 4.2 Low Energy (LE)



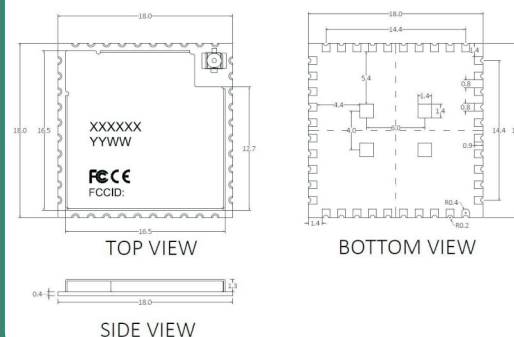
General	
Chipset	MT7697
Core	ARM Cortex-M4 MCU
FPU Clock Speed	192MHz
SRAM	352KB
External Flash	4MB
Antenna connector	MHF4 series: 20449-001E
Operation Condition	
Temperature	Operating : -40°C ~ +85°C
	Storage : -40°C ~ +105°C
Humidity	Operating : 10 ~ 95% (Non-Condensing)
	Storage : 5 ~ 95% (Non-Condensing)
Mechanical Information	
Dimension	18mm X 18mm X 1.7mm (Typ.)
Package	LGA 44Pin – Stamp hole type
Certification	
CE FCC	

Electrical Characteristics					
Symbol	Parameter	Min.	Typ.	Max.	Unit
VBAT	Supply Voltage	3	3.3	3.6	V
I/O Voltage	I/O supply voltage	3	3.3	3.6	V

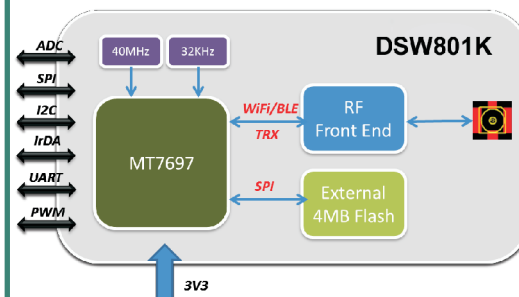
Product quick glance



ME Drawing/placement



Block Diagram



Ordering Information

PART NUMBER	DESCRIPTION



We are Your Partner more than Business



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